SCLS520B - AUGUST 2003 - REVISED MAY 2004

- **Qualification in Accordance With** AEC-Q100†
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control** Can Be Supported Along With Major-Change Approval
- 2-V to 5.5-V V_{CC} Operation
- **Supports Mixed-Mode Voltage Operation on All Ports**
- **High On-Off Output-Voltage Ratio**
- Low Crosstalk Between Switches
- **Individual Switch Controls**
- **Extremely Low Input Current**
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

D, DW, OR PW PACKAGE (TOP VIEW) 16 🛮 V_{CC} Υ4 Y6 🛮 2 15 Y2 сом Пз 14 Y1 Y7 🛮 4 13 Y0 12 Y3 Y5 Π_5 INH 11 🛮 A GND II 7 10 B 9 🛮 C GND I

description/ordering information

This 8-channel CMOS analog multiplexer/demultiplexer is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV4051A handles both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

TA	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - D	Tape and reel	SN74LV4051ATDRQ1	L4051AQ
-40°C to 105°C	SOIC - DW	Tape and reel	SN74LV4051ATDWRQ1	L4051AQ
	TSSOP - PW	Tape and reel	SN74LV4051ATPWRQ1	L4051AQ

[‡]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

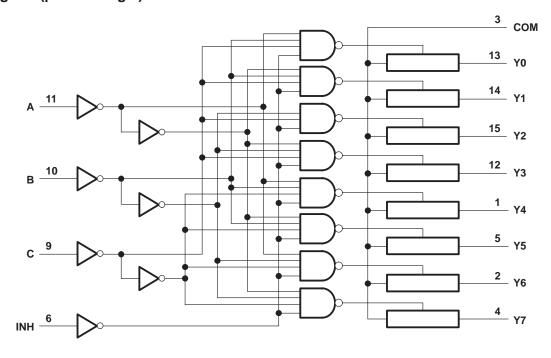


[†] Contact factory for details. Q100 qualification data available on request.

FUNCTION TABLE

	INP	ON		
INH	С	В	CHANNEL	
L	L	L	L	Y0
L	L	L	Н	Y1
L	L	Н	L	Y2
L	L	Н	Н	Y3
L	Н	L	L	Y4
L	Н	L	Н	Y5
L	Н	Н	L	Y6
L	Н	Н	Н	Y7
Н	Χ	X	Χ	None

logic diagram (positive logic)



SCLS520B - AUGUST 2003 - REVISED MAY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

pply voltage range, V _{CC}	
ut voltage range, V _I (see Note 1)	
itch I/O voltage range, V _{IO} (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
ut clamp current, I _{IK} (V _I < 0)	–20 mA
diode current, I _{IOK} (V _{IO} < 0)	–50 mA
itch through current, I _T (V _{IO} = 0 to V _{CC})	±25 mA
ntinuous current through V _{CC} or GND	±50 mA
ckage thermal impedance, $\hat{\theta}_{JA}$ (see Note 3): D package	95°C/W
DW package	
PW package	
orage temperature range, T _{sta}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		2‡	5.5	V	
		V _{CC} = 2 V	1.5			
.,	High-level input voltage,	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$.,	
VIH	control inputs	V _{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		V	
		V _{CC} = 4.5 V to 5.5 V	$V_{CC} \times 0.7$			
		V _{CC} = 2 V		0.5		
	' ° '	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V	
VIL	control inputs	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$		
٧ _I	Control input voltage		0	5.5	V	
V _{IO}	Input/output voltage		0	VCC	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		
TA	Operating free-air temperature		-40	105	°C	

[‡] With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SCLS520B - AUGUST 2003 - REVISED MAY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				T,	Δ = 25°C	;			
	PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		I _T = 2 mA,	2.3 V		38	180		225	
ron	On-state switch resistance	V _I = V _{CC} or GND, V _{INH} = V _{IL}	3 V		30	150		190	Ω
SWIGHTESISIANOS		(see Figure 1)	4.5 V		22	75		100	
		I _T = 2 mA,	2.3 V		113	500		600	
ron(p)	Peak on-state resistance	$V_I = V_{CC}$ to GND,	3 V		54	180		225	Ω
···(P)		V _{INH} = V _{IL}	4.5 V		31	100		125	
	Difference in	$I_T = 2 \text{ mA},$	2.3 V		2.1	30		40	
Δr_{on}	on-state resistance	$V_I = V_{CC}$ to GND,	3 V		1.4	20		30	Ω
between switches	VINH = VIL	4.5 V		1.3	15		20		
IJ	Control input current	V _I = 5.5 V or GND	0 to 5.5 V			±0.1		±1	μΑ
IS(off)	Off-state switch leakage current	$V_I = V_{CC}$ and $V_O = GND$, or $V_I = GND$ and $V_O = V_{CC}$, $V_{INH} = V_{IH}$ (see Figure 2)	5.5 V			±0.1		±1	μΑ
I _{S(on)}	On-state switch leakage current	V _I = V _{CC} or GND, V _{INH} = V _{IL} (see Figure 3)	5.5 V			±0.1		±1	μА
ICC	Supply current	V _I = V _{CC} or GND	5.5 V					20	μΑ
C _{IC}	Control input capacitance	f = 10 MHz	3.3 V		2				pF
C _{IS}	Common terminal capacitance		3.3 V		23.4				pF
COS	Switch terminal capacitance		3.3 V		5.7				pF
CF	Feedthrough capacitance		3.3 V		0.5				pF



SCLS520B - AUGUST 2003 - REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

DADAMETED		FROM	то	TEST	T _A = 25°C					
PAI	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 50 pF, (see Figure 4)		2.5	9		12	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		5.5	20		25	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		8.8	20		25	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted)

DAT	DAMETER	FROM	то	TEST	T _A = 25°C			BAILL BAAY		
PAR	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 50 pF, (see Figure 4)		1.5	6		8	ns
tPZH tPZL	Enable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		4	14		18	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		6.2	14		18	ns

SCLS520B - AUGUST 2003 - REVISED MAY 2004

analog switch characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	FROM	то	7507.00	NIDITIONIO.	.,	T,	λ = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	TEST CO	NDITIONS	VCC	MIN	TYP	MAX	UNIT		
					$C_L = 50 \text{ pF},$		2.3 V		20		
Frequency response (switch on)	COM or Yn	COM or Yn Y	COM or Yn Yn or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sin	e wave)	3 V		25		MHz	
(ermen err)			(see Note 5 and		4.5 V		35				
			$C_L = 50 \text{ pF},$ $R_L = 600 \Omega,$ $f_{in} = 1 \text{ MHz (square wave)}$		2.3 V		20				
Crosstalk (control input to signal output)	INH	COM or Yn			3 V		35		mV		
(control input to digital output)			(see Figure 7)	uaic wave)	4.5 V		60				
			C _L = 50 pF,		2.3 V -45						
Feedthrough attenuation (switch off)	COM or Yn	Yn or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$		3 V		-45		dB		
(cuiton cii)			(see Note 6 and	d Figure 8)	4.5 V		-45				
			C _L = 50 pF,	V _I = 2 V _{p-p}	2.3 V		0.1				
Sine-wave distortion	COM or Yn	Yn or COM	$R_L = 10 \text{ k}\Omega$, $f_{\text{in}} = 1 \text{ kHz}$	V _I = 2.5 V _{p-p}	3 V	·	0.1	·	%		
			(sine wave) (see Figure 9)	V _I = 4 V _{p-p}	4.5 V	·	0.1				

NOTES: 5. Adjust f_{in} voltage to obtain 0-dBm output. Increase f_{in} frequency until dB meter reads -3 dB.

operating characteristics, $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	$C_L = 50 pF$,	f = 10 MHz	5.9	pF

PARAMETER MEASUREMENT INFORMATION

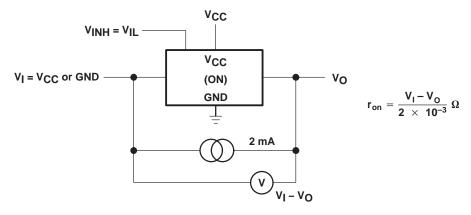
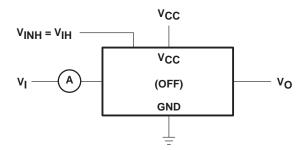


Figure 1. On-State Resistance Test Circuit

^{6.} Adjust fin voltage to obtain 0-dBm input.

PARAMETER MEASUREMENT INFORMATION



Condition 1: $V_I = 0$, $V_O = V_{CC}$ Condition 2: $V_I = V_{CC}$, $V_O = 0$

Figure 2. Off-State Switch Leakage-Current Test Circuit

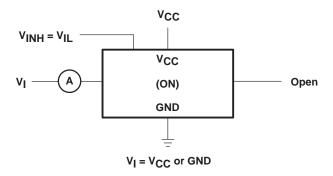


Figure 3. On-State Switch Leakage-Current Test Circuit

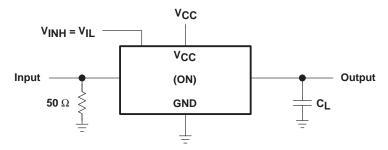


Figure 4. Propagation Delay Time, Signal Input to Signal Output

PARAMETER MEASUREMENT INFORMATION

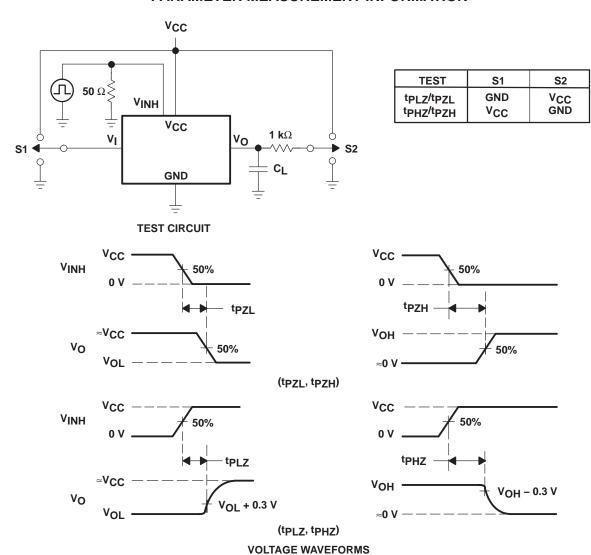


Figure 5. Switching Time (t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}), Control to Signal Output

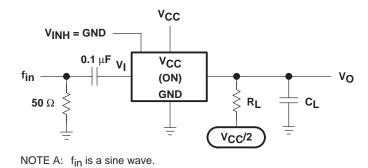


Figure 6. Frequency Response (Switch On)



PARAMETER MEASUREMENT INFORMATION

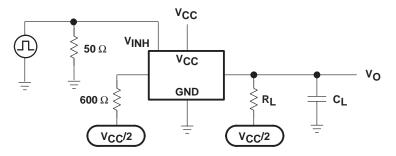


Figure 7. Crosstalk (Control Input, Switch Output)

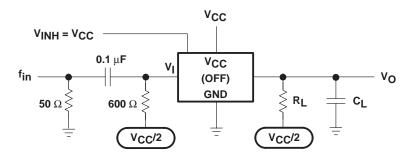


Figure 8. Feedthrough Attenuation (Switch Off)

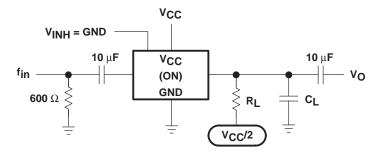


Figure 9. Sine-Wave Distortion





.com 24-Jun-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV4051ATDRQ1	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LV4051ATDWRQ1	ACTIVE	SOIC	DW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LV4051ATPWRQ1	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

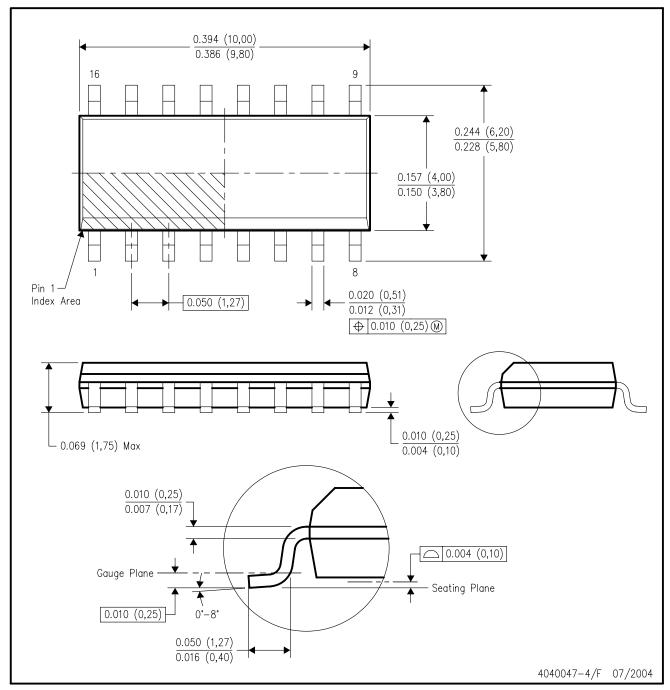
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



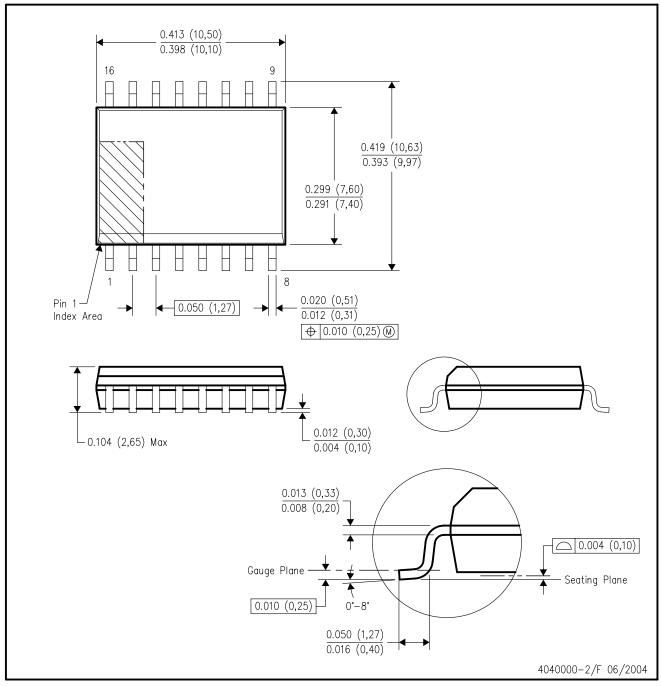
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated